

IN THE ABSTRACT:

Please replace page 19 with the following substitute page 19, which includes a rewritten Abstract as follows:

1 Apparatus and methods for testing conductive bumps or target test points
2 on integrated circuits, comprising A a multiplicity of probes are extended
3 extending through a support substrate. At least one of the multiplicity of probe
4 locations include including a second electrically isolated probe such that the test
5 point is in contact with two probes. One of the two probes provides providing a
6 voltage to the test point and the second probe sensing the voltage so as to
7 provide a Kelvin connection.

MULTIPLE CONTACT VERTICAL PROBE SOLUTION ENABLING KELVIN CONNECTION BENEFITS FOR CONDUCTIVE BUMP PROBING

Abstract

Apparatus and methods for testing conductive bumps or target test points on integrated circuits. A multiplicity of probes are extended through a support substrate. At least one of the multiplicity of probe locations include a second electrically isolated probe such that the test point is in contact with two probes. One of the two probes provides a voltage to the test point and the second probe sensing the voltage so as to provide a Kelvin connection.